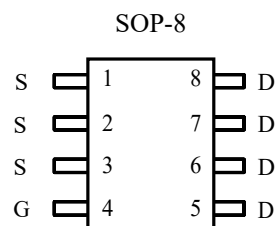


N -Channel High Density Trench MOSFET

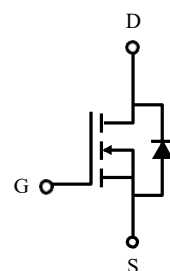
Features:

- Super high dense cell trench design for low RDS(on).
- Rugged and reliable.
- Surface Mount package.



PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(on)}$ (mΩ) Max	I_D
30V	8 @ $V_{GS} = 10V$	20A
	9.5 @ $V_{GS} = 4.5V$	



ABSOLUTE MAXIMUM RATINGS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous (Note 1) @ $T_A = 25\text{ °C}$ -Pulse (Note 2)	I_D	20	A
	I_{DM}	80	
Maximum Power Dissipation (Note 1)	P_D	$T_A=25\text{ °C}$	3.2
		$T_A=75\text{ °C}$	2.0
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 1)	R_{thJA}	42	°C/W
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Note:

1. Surface Mounted on FR4 Board , $t \leq 10\text{sec}$.
2. Pulse width limited by maximum junction temperature

ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

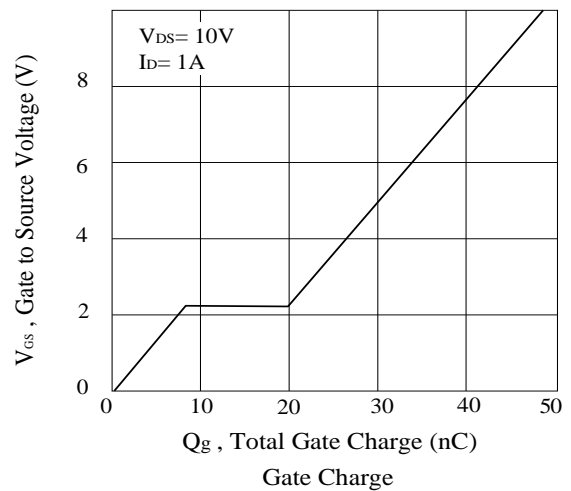
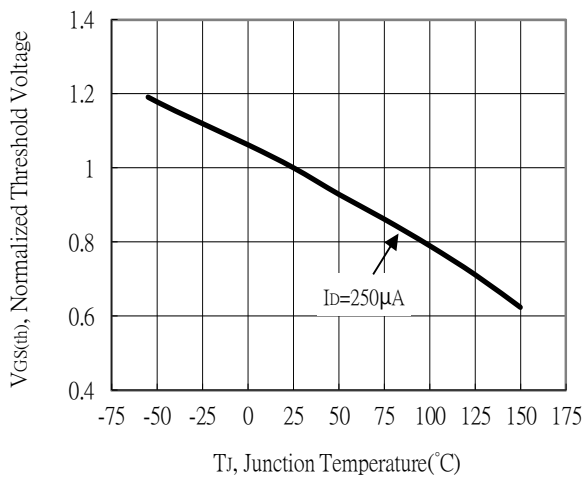
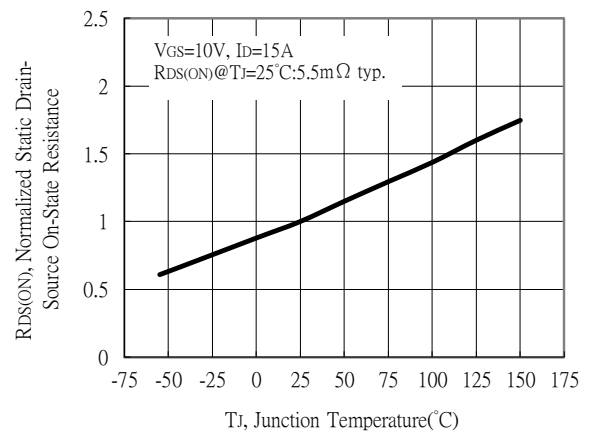
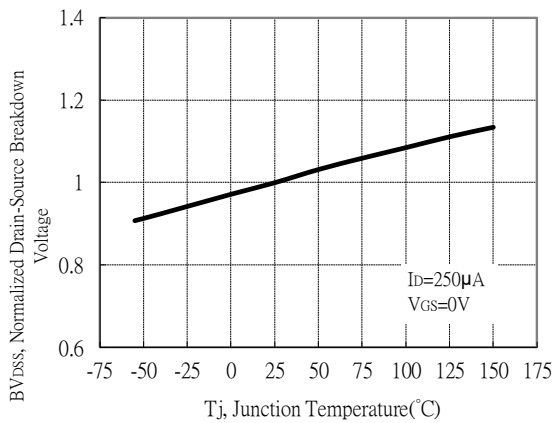
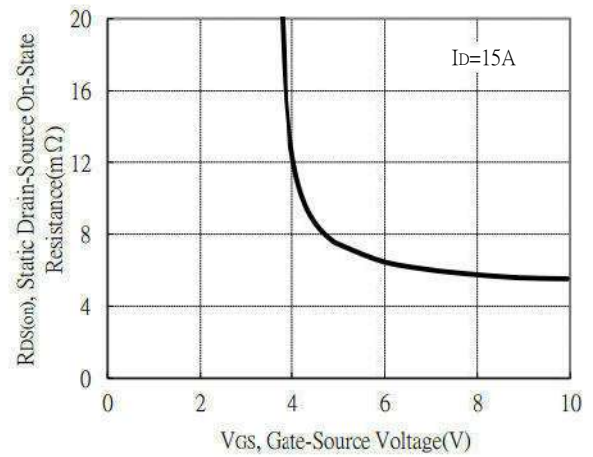
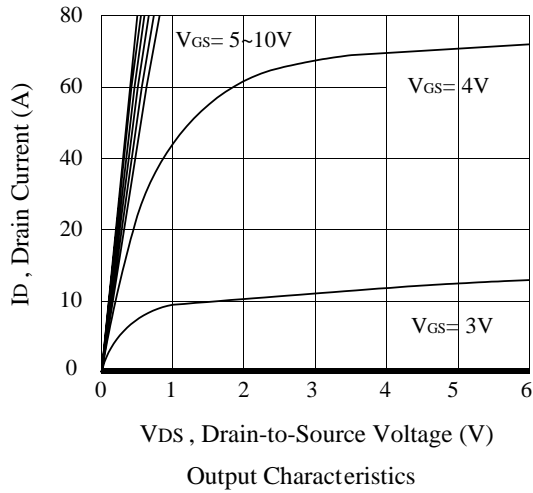
Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	3	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$		5.5	8	m Ω
		$V_{GS} = 4.5V, I_D = 9A$		6.8	9.5	m Ω
Forward Transconductance	gfs	$V_{DS} = 15V, I_D = 12.5A$		22		S
DYNAMIC CHARACTERISTICS (Note 4)						
Input Capacitance	C_{ISS}	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0MHz$		1860		pF
Output Capacitance	C_{OSS}			260		pF
Reverse Transfer Capacitance	C_{RSS}			212		pF
SWITCHING CHARACTERISTICS (Note 4)						
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} = 15V, I_D = 1A, V_{GEN} = 10V, R_{GEN} = 6\Omega, R_L = 15\Omega$		9.6		nS
Rise Time	tr			23.4		nS
Turn-Off Delay Time	$t_{d(OFF)}$			62.8		nS
Fall Time	tf			23		nS
Total Gate Charge	Qg	$V_{DS} = 10V, I_D = 1A$ $V_{GS} = 10V$		48		nC
Gate-Source Charge	Qgs			3.4		nC
Gate-Drain Charge	Qgd			14		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Drain-Source Diode Forward Current (Note 1)	I_S			8		A
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS} = 0V, I_S = 1.0A$		0.7	1.1	V

Note:

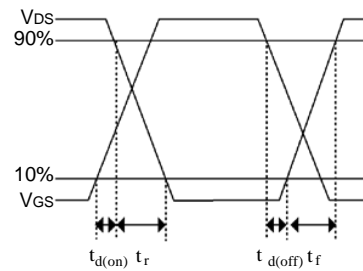
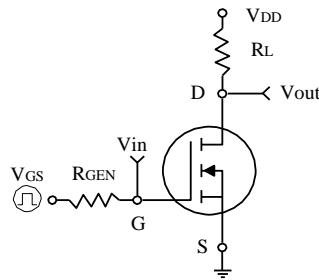
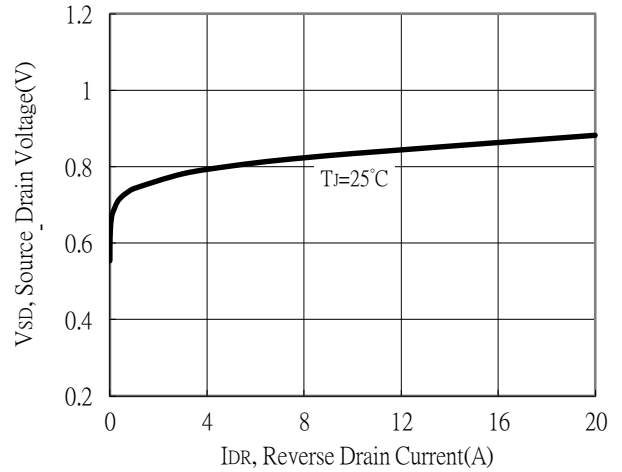
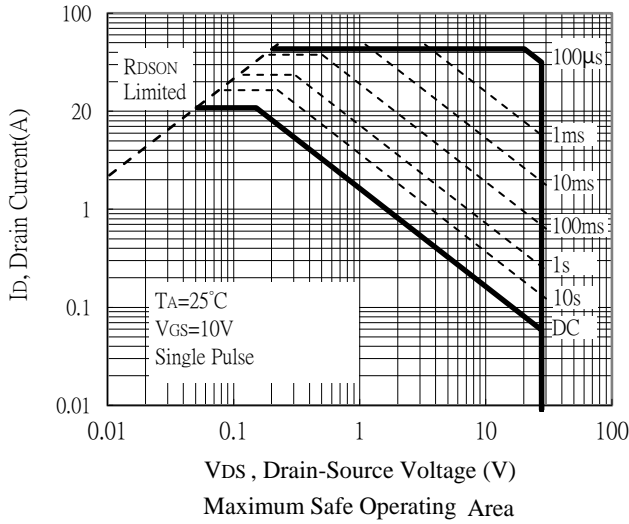
3. Pulse Test Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

4. Guaranteed by design, not subject to production testing.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



Switching Test Circuit and Switching Waveforms

Transient Thermal Response Curves

